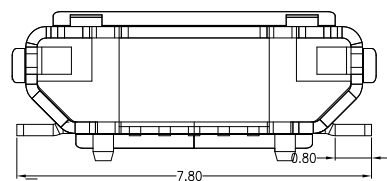
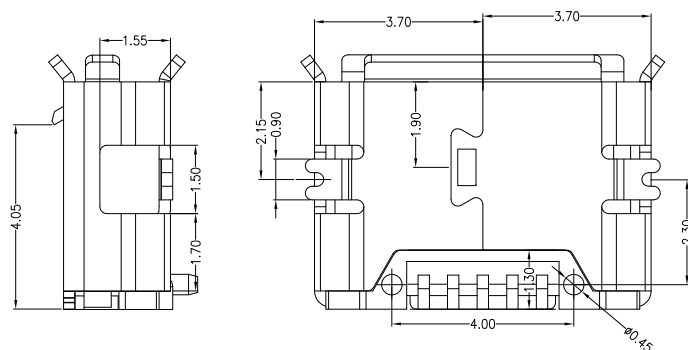
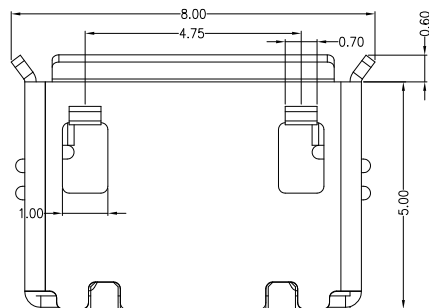


RECOMMENDED PCB LAYOUT



**NOTES:**

**1. Material:**

Housing: High Temperature Thermoplastic with G.F., UL94 V-0.  
 Color: Black.  
 Contact: Copper Alloy, T=0.20mm.  
 Plating: Gold Plating over Nickel(50u") on Contact Area,  
 Tin(80u"~100u") Plating over Nickel(50u") on Solder Tail.  
 Shield: Copper Alloy, T=0.25mm.  
 Plating: Nickel(100u"~120u") Plating.

**2. Mechanical:**

Insertion Force: 3.57Kgf Max.  
 Withdrawal Force: 1.0Kgf Min Initial, 0.81~2.05Kgf after 10000Cycles.  
 Durability: 10000Cycles.

**3. Electrical Specification:**

Current Rating: 1.0Ampere at 30VDC.  
 Contact Resistance: 30mΩ Max Initial, 50mΩ after 1000Cycles.  
 Insulation Resistance: 100MΩ Min.  
 Dielectric Withstanding Voltage: 100 VAC per Minute.

**4. Environmental:**

Operating Temperature: -30°C to +80°C

**Part Number:**

**CU2M-R05RSG0-P1**

USB2.0 Micro Type  
 R: Receptacle  
 05: 5Pins  
 R: Right Angle

Product Number  
 P1: Micro B, With Posts 4.0mm  
 0: Black  
 G: Gold Flash  
 S: SMT Type

A	07/21/11	RELEASED FOR PRODUCTION	
REV	DATE	DESCRIPTION	
UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN MM TOLERANCES ARE:		CAD GENERATED DRAWING, DO NOT MANUALLY UPDATE	
DECIMALS	ANGLES	APPROVALS	DATE
.X ± .38	± 3°	DRAWN Chris	07/21/11
.XX ± .25		CHECKED Cindy	07/21/11
.XXX ± .20		APPV Jason	07/21/11
DO NOT SCALE DRAWING		SHEET 1 OF 1	SCALE NONE
		DWG. NO.	CU2M-R05-0P1
		REV.	A



DESCRIPTION USB2.0 Micro B Type, 5Pins, Receptacle, R/A SMT, Gold Flash, With Plastic Posts, Distance 4.0mm